

INFORMATION DISCLOSURE CITATION
IN AN APPLICATION FEB 17 2

(Use several sheets if necessary)

FEB 17 2004

Document Number (Optional)

TSMC-03-299

Customer Number

101714, 985

"William Hong, et al.

11/17/03

Drawn in Unit 2813

RE
PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (including Author, Title, Date, Portion or Pages, Etc.)

TP	-	Co-pending U.S. Patent TSMC-02-992, Serial # 10/723,236, filed on 11/26/03, same assignee, "An Advanced Process Control Approach for Cu Interconnect Wiring Sheet Resistance Control"
TW	-	Co-pending U.S. Patent TSMC-03-424, Serial # 10/627,795, filed on 07/25/03, same assignee, "Barrier-Slurry-Free Copper CMP Process".
TW	-	

Examiner

W. H. Blair

DATE CONSIDERED

1/3/105

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.